

Title (en)  
GAP FILLING PROFILE

Title (de)  
FUGENFÜLLUNGSPROFIL

Title (fr)  
PROFILÉ DE REMPLISSAGE DE JOINT

Publication  
**EP 3757313 A1 20201230 (DE)**

Application  
**EP 20185359 A 20170505**

Priority  

- DE 202016102430 U 20160506
- EP 18205299 A 20170505
- EP 17169622 A 20170505

Abstract (en)  
[origin: CA2966467A1] The invention relates to a joint filling profile for forming a joint sealing between floor panels (3, 4), with a vertical leg (6) that projects into the joint (2) and a profile body (7) formed from a joint sealing compound (9) and situated in a joint enlargement (5), whereby the vertical leg (6) and the profile body (7) are separated from each other by intercalating a separating material (8).

Abstract (de)  
Die Erfindung betrifft ein Fugenfüllungsprofil zur Ausbildung einer Fugenabdichtung zwischen Bodenplatten (3, 4), mit einem in die Fuge (2) ragenden Vertikalschenkel (6) und einem aus einer Fugenvergussmasse (9) gebildeten und in einer Fugenverbreiterung (5) liegenden Profilkörper (7), wobei der Vertikalschenkel (6) und der Profilkörper (7) unter Zwischenordnung eines Trennmaterials (8) voneinander separiert sind.

IPC 8 full level  
**E04F 15/02** (2006.01); **E01C 11/02** (2006.01); **E04B 1/68** (2006.01); **E04F 15/14** (2006.01)

CPC (source: EP US)  
**E04B 1/6804** (2013.01 - EP US); **E04F 15/02016** (2013.01 - EP US); **E04F 15/02033** (2013.01 - EP US); **E04F 15/14** (2013.01 - EP US)

Citation (applicant)  

- DE 10002866 B4 20080207 - SK WIEGRINK BETEILIGUNGS GMBH [DE]
- EP 2098651 A2 20090909 - SK WIEGRINK BETEILIGUNGS GMBH [DE]
- EP 0445341 A1 19910911 - STELCON AG [DE]
- WO 2007053119 A1 20070510 - UNIV SINGAPORE [SG], et al
- EP 0209865 A2 19870128 - MATSUSHITA ELECTRIC IND CO LTD [JP]

Citation (search report)  

- [XYI] EP 0445341 A1 19910911 - STELCON AG [DE]
- [XP] DE 102015118223 A1 20170427 - IBOTAC GMBH & CO KG [DE]
- [Y] WO 2007053119 A1 20070510 - UNIV SINGAPORE [SG], et al
- [Y] AU 2007201116 A1 20080403 - DENNY DAVID JOHN [AU]
- [Y] DE 102006021426 A1 20071115 - SPANN THORSTEN [DE]

Citation (examination)  
US 8790038 B2 20140729 - STACHOWICZ MICHAEL F [US], et al

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**DE 202016102430 U1 20170809**; CA 2966467 A1 20171106; CA 2966467 C 20200512; EP 3241953 A1 20171108; EP 3241953 B1 20190710; EP 3412842 A1 20181212; EP 3412842 B1 20190717; EP 3460135 A1 20190327; EP 3460135 B1 20210127; EP 3757313 A1 20201230; US 10577806 B2 20200303; US 2017321432 A1 20171109

DOCDB simple family (application)  
**DE 202016102430 U 20160506**; CA 2966467 A 20170510; EP 17169622 A 20170505; EP 18185489 A 20170505; EP 18205299 A 20170505; EP 20185359 A 20170505; US 201715589128 A 20170508